

RoHS Compliant



Description:

MLCC consists of a conducting material and electrodes. To manufacture a chip-type SMT and achieve miniaturization, high density and high efficiency, ceramic condensers are used. 0201 MLCC is performed by high precision technology achieve high capacitance in unit size and ensure the stability and reliability of products.

Features:

- High capacitance in unit size.
- · High precision dimensional tolerances.
- Suitable used in high-accuracy automatic mounting machine.

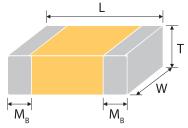
Applications:

- · Miniature microwave module.
- Portable equipments (ex. Mobile phone, PDA).
- · High frequency circuits.

How To Order:

мс	31	Х	225	K	100	С	Т
IVIC	<u>Size</u>	Dielectric	<u>Capacitance</u>	<u>Tolerance</u>	Rated Voltage	<u>Termination</u>	Packaging style
Туре	Inch (mm) 0201 (0603)	N=NP0 (C0G) B=X7R X=X5R	Two significant digits followed by no. of zeros. And R is in place of decimal point. Eg.: 0R5 = 0.5pF 1R0 = 1.0pF 102 = 10x10 ² = 1,000pF	A=±0.05pF B=±0.1pF C=±0.25pF D=±0.5pF F=±1% G=±2% J=±5% K=±10% M=±20% Z=-20/+80%	Two significant digits followed by no. of zeros. And R is in place of decimal point. 6R3=6.3V DC 100=10V DC 160=16V DC 250=25V DC 500=50V DC	C=Cu/Ni/Sn	T = 7" reeled

External Dimensions:



The outline of MLCC

Size Inch (mm)	L (mm)	W (mm)	T max (mm)/Symbol		М _в (mm)
0204 (0602)	0.6 ±0.03	0.30±0.03	0.3 ±0.03		0.15 ±0.05
0201 (0603)	0.6 ±0.05 ^{#1}	0.3±0.05 ^{#1}	0.3 ±0.05 ^{#1}		0.15 ±0.05

^{*} Reflow soldering only. #1 For 0201/Cap≧0.68uF





General Electrical Data:

Size	0201				
Dielectric	NP0	X7R	X5R		
Capacitance*	0.1pF to 120pF	100pF to 10nF	100pF to 1μF		
Capacitance tolerance**	Cap≤5pF ^{#1} : A (±0.05pF), B (±0.1pF), C	J (±5%), K (±10%), M (±20%)	J (±5%),K (±10%), M (±20%)		
Rated voltage (WVDC)	16V, 25V, 50V	6.3V, 10V, 16V, 25V, 50V	6.3V, 10V, 16V, 25V, 50V		
Tan δ / Q* Cap<30pF, Q≥400+200		Note 1			
Insulation resistance ≥10GΩ		≥10GΩ or RxC≥500ΩxF whichever is less			
Operating temperature	-55 to -	+125°C	-55 to +85°C		
Capacitance change	±30ppm	±30ppm ±15%			
Termination	Ni/Sn (lead-free termination)				

^{#1:} NP0, 0.1pF product only provide B tolerance

NP0: Apply 1.0±0.2Vrms, 1.0MHz±10% at the condition of 25°C ambient temperature.

X7R, X5R: Apply 1.0±0.2Vrms, 1.0kHz±10%(0201/6.3V,Cap≥224 : 0.5±0.2Vrms, 1.0kHz±10%) at the condition of 25°C ambient temperature.

Note 1: X7R/X5R

Rated vol.	D.F.	Exception of D.F.		
≥50V	≤3%	-		
25V	≤3.5%	≤5%	0201≥0.01µF	
16V	≤3.5%	≤5%	0201≥0.01µF	
10V	≤5%	≤10%	0201≥0.012µF	
100	≥5%	≤15%	0201≥0.1µF	
6.3V	≤10%	≤15%	0201≥0.1µF	

^{*} Measured at 30~70% related humidity.

^{**} Preconditioning for Class II MLCC: Perform a heat treatment at 150±10°C for 1 hour, then leave in ambient condition for 24±2 hours before measurement.



Packaging Dimension And Quantity:

Size	Thickness (mm\/Cvmbol	Paper tape		
Size	i i i i i i i i i i i i i i i i i i i	mm)/Symbol	7" reel	13" reel	
0204 (0602)	0.3 ±0.03	_	15,000	70,000	
0201 (0603)	0.3 ±0.05 ^{#1}	L	15,000	-	

Unit: pieces

Reliability Test Conditions and Requirements:

No	Item	Test Condition		Requirements			
1	Visual and Mechanical	-		markable defect. sions to conForm to individual specification sheet.			
2	Capacitance		Shall not exce	eed the limits	given in th	ne detailed spec.	
		Class I: NP0	NP0: Cap≥30 X7R, X5R:	pF, Q≥1000;	Cap<30pF	F, Q≥400+20C	
		Cap≤1000pF, 1.0±0.2Vrms, 1MHz±10%	Rated vol.	D.F	Exc	eption of D.F.	
	Q/ D.F.	Cap>1000pF, 1.0±0.2Vrms, 1KHz±10%	≥50V	≤3%	-		
3	(Dissipation	Class II: X7R, X5R 1.0±0.2Vrms, 1kHz±10%**	25V	≤3.5%	≤5%	0201≥0.01µF	
	Factor)	**0.5±0.2Vrms, 1.0kHz±10% : 0201	16V	≤3.5%	≤5%	0201≥0.01µF	
		≥0.22 uF(6.3V)	10V	ZE0/	≤10%	0201≥0.012µF	
				≤5%	≤15%	0201≥0.1µF	
				≤10%	≤15%	0201≥0.1µF	
4	Dielectric Strength	To apply voltage (≤100V) 250%. Duration: 1 to 5 sec. Charge and discharge current less than 50mA.	No evidence	of damage o	r flash ove	r during test.	
	Insulation		≥10GΩ or Rx Class II (X5R	, X6S, X7R, `	Y5V)		
5	Resistance	To apply rated voltage for max. 120sec.	Rated voltag		Insulation	n resistance	
			6.3V; 10V:0201≥47nF		≥100 Ω-F		
		With no electrical load.	T-0	10	01		
		T.C. Operating Temp	T.C.		ice Change	<u>e</u>	
6	6 Temperature Coefficient	NP0 (C0G) 55~125°C at 25°C	NP0 (C0G)		Within ±30ppm/°C		
	Coemcient	X7R 55~125°C at 25°C	X7R	11101111	Within ±15%		
		X5R 25~85°C at 20°C	X5R	Within ±15	0 %		
7.	Adhesive Strength of Termination	Pressurizing force : 2N Test time: 10±1 sec.	No remarkabl	le damage or	removal c	of the terminations.	





No	Item		Test Condition		Requirements	
8	Vibration Resistance	Vibration frequency: 10~55 Hz/min. Total amplitude: 1.5mm Test time: 6 hrs. (Two hrs each in three mutually perpendicular directions.) Measurement to be made after keeping at room temp. for 24±2 hrs.		n three s.)	No remarkable damage. Cap change and Q/D.F.: To meet initial spec.	
9	Solderability		temperature: 235±5°C g time: 2±0.5 sec.		95% min. coverage of all metalized area	
10	Bending Test	The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1mm per second until the deflection becomes: 5mm and then the pressure shall be maintained for 5±1 sec. Measurement to be made after keeping at room temp. for 24±2 hrs.		essur- per mes : Il be	No remarkable damage. Cap change: NP0: within ±5.0% or ±0.5pF whichever is larger. X7R, X5R: within ±12.5% Y5V: within ±30% (This capacitance change means the change of capacitance under specified flexure of substrate from the capacitance measured before the test.)	
11	Resistance to Soldering Heat	Solder temperature: 260±5°C Dipping time: 10±1 sec Preheating: 120 to 150°C for 1 minute before immerse the capacitor in a eutectic solder. Before initial measurement (Class II only): Perform 150+0/-10°C for 1 hr and then set for 24±2 hrs at room temp. Measurement to be made after keeping at room temp. for 24±2 hrs.		or in a ss II 1 hr and mp.	No remarkable damage. Cap change: NP0: within ±2.5% or ±0.25pF whichever is larger. X7R, X5R: within ±7.5% Y5V: within ±20% Q/D.F., I.R. and dielectric strength: To meet initial requirements. 25% max. leaching on each edge.	
			ct the five cycles accordir	ng to		
		Step	Temp. (°C)	Time (min.)	No remarkable damage.	
	12 Temperature Cycle	1	Min. operating temp. +0/-3	30±3	Cap change:	
12		2	Room temp.	2~3	NP0: within ±2.5% or ±0.25pF whichever is larger. X7R, X5R: within ±7.5%	
'-		3	Max. operating temp. +3/-0	30±3	Y5V: within ±20%	
		4	Room temp.	2~3	Q/D.F., I.R. and dielectric strength: To meet initial	
			initial measurement (Class II n 150+0/-10°C for 1 hr and th 2 hrs at room temp. ement to be made after keep emp. for 24±2 hrs.	en set	requirements.	





No	Item	Test Condition	Requirements			ts
13	Humidity (Damp Heat) Steady State	Test temp.: 40±2°C Humidity: 90~95% RH Test time: 500+24/-0hrs. Before initial measurement (Class II only): Perform 150+0/-10°C for 1 hr and then set for 24±2 hrs at room temp Measurement to be made after keeping	Q/D.F. value: NP0: Cap≥30pf Cap<10pF; Q≥2 X7R, X5R: Rated vol. ≥50V	IP0: within ±5 (7R, X5R: ≥10 10\ 6.3' 5V: ≥10V, with 6.3V, with F, Q≥350; 10p 200+10C D.F ≤6%	IV, within ±1: /≧ 0.1µF, wi V, within ±25 hin ±30% hin ±30/-40% IF≤Cap<30p Exc	thin ±25%; 5% F, Q≥275+2.5C ception of D.F.
		at room temp. for 24±2 hrs.	25V 16V	≤5% ≤5%	≤10%	0201≥0.01µF
			100	≥5%	≤15% ≤15%	0201≥0.01µF 0201≥0.012µF
			10V	≤7.5%	≤20%	0201≥0.1µF
			6.3V	≤15%	≤30%	0201≥0.1µF
			I.R.: ≥10V, ≥1GΩ or RxC≥50Ω-F whichever is smaller. 6.3V; 10V:0201≥47nF, RxC≥10Ω-F			
	Humidity	Test temp.: 40±2°C Humidity: 90~95%RH Test time: 500+24/-0 hrs. To apply voltage : rated voltage	2) 1 6 Y Q/D.F. value:	NP0: within ±: (7R, X5R: ≥: 10V≧ 0.1µF, 6.3V, within ±: (5V: ≥10V, within ±: 6.3V, within ±:	10V, within within ±25 ⁶ :25% within ±30% thin +30/-4	%;
14	(Damp Heat)	Before initial measurement (Class II only): To apply test voltage for 1hr at	Rated vol.	D.F	Exc	eption of D.F.
	Load	40°C and then set for 24±2 hrs at room	≥50V	≤6%		
		temp.	25V	≤5%	≤10%	0201≥0.01µF
		Measurement to be made after keeping at room temp. for 24±2 hrs.	16V	≤5%	≤15%	0201≥0.01µF
		·	10V	≤7.5%	≤15%	0201≥0.012µF
					≤20%	0201≥0.1µF
			6.3V	≤15%	≤30%	0201≥0.1μF
				0MΩ or RxC V:0201≥47nl		ichever is smaller. -F

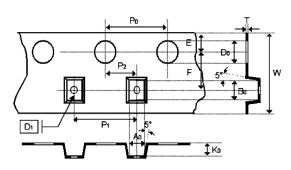




No	Item	Test Condition	Requirements			ts
	High	Test temp.: NP0, X7R: 125±3°C X5R,Y5V: 85±3°C To apply voltage: 1) Cap.≥0.1uF: 100% of rated voltage 2) 6.3V: 150% of rated voltage. 3) >6.3V: 200% of rated voltage. Test time: 1,000+24/-0 hrs. Before initial measurement (Class II only): To apply test voltage for 1hr at test temp. and then set for 24±2 hrs at	No remarkable damage. Cap change: NP0: within $\pm 3.0\%$ or ± 0.3 pF whichever is larger. X7R, X5R: ≥ 10 V, within $\pm 12.5\%$, 10 V ≥ 0.1 µF, within $\pm 25\%$; 6.3V, within $\pm 25\%$ Y5V: ≥ 10 V, within $\pm 30\%$ 6.3V, within ± 30 /-40% Q/D.F. value: NP0: Cap ≥ 30 pF, Q ≥ 350 ; 10 pF $\leq Cap<30$ pF, Q $\geq 275+2.5$ C Cap ≤ 10 pF; Q $\geq 200+10$ C X7R/X5R:			
15	Temperature Load	Measurement to be made after keeping	Rated vol.	D.F	Exc	eption of D.F.
	(Endurance)		≥50V	≤6%	-	
			25V	≤5%	≤10%	0201≥0.01µF
			16V	≤5%	≤15%	0201≥0.01µF
			10V	≤7.5%	≤15%	0201≥0.012µF
			100	≥7.5%	≤20%	0201≥0.1µF
			6.3V	≤15%	≤30%	0201≥0.1µF
			·	GΩ or RxC≥ V:0201≥47nl		chever is smaller. Ω-F

Appendixes

Tape & Reel Dimensions

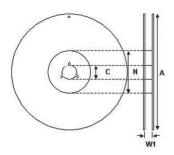


The dimension of plastic tape

Size	0201
Thickness	L
A ₀	0.38±0.05
Bo	0.68±0.05
Т	0.42±0.05
K ₀	-
W	8.00±0.10
P ₀	4.00±0.10
10xP₀	40.0±0.10
P ₁	2.00±0.05
P ₂	2.00±0.05
D ₀	1.55±0.05
D ₁	-
E	1.75±0.05
F	3.50±0.05



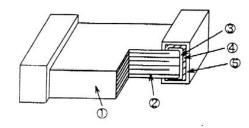




Size	0201			
Reel size	7"	13"		
С	13 +0.5/-0.2	13 +0.5/-0.2		
W1	8.4 +1.5/-0	8.4 +1.5/-0		
А	178 ±0.10	330 ±1		
N	60 +1/-0	100 ±1		

The dimension of reel

Constructions:



No.	Na	me	NPO, X7R, Y5V
1	Ceramic	material	BaTiO₃ based
2	Inner el	ectrode	Ni
3		Inner layer	Cu
4	Termination	Middle layer	Ni
5		Outer layer	Sn (Matt)

Storage and handling conditions

- (1) To store products at 5°C to 40°C ambient temperature and 20 to 70%. related humidity conditions.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

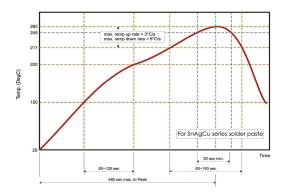
Cautions:

- a. The corrosive gas reacts on the terminal electrodes of capacitors, and results in the poor solderability.
 Do not store the capacitors in the ambience of corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine, ammonia gas etc.)
- b. In corrosive atmosphere, solderability might be degraded, and silver migration might occur to cause low reliability.
- c. Due to the dewing by rapid humidity change, or the photochemical change of the terminal electrode by direct sunlight, the solderability and electrical performance may deteriorate. Do not store capacitors under direct sunlight or dewing condition. To store products on the shelf and avoid exposure to moisture.

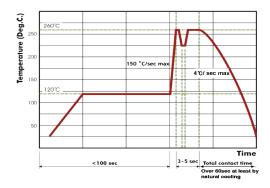


Recommended Soldering Conditions:

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of N_2 within oven are recommended.



Recommended reflow soldering profile for SMT process with SnAgCu series solder paste.



Recommended wave soldering profile for SMT process with SnAgCu series solder.

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